IN THE CLAIMS:

1. (original) A flake-form conductive compound characterized as comprising titanium oxide having an average major diameter of 1 - 100 μm and an average thickness of 0.01 - 1.5 μm and containing 0.3 - 5 % by weight of potassium in terms of potassium oxide (K_2O), a first conductive layer comprising tin oxide containing antimony and provided on a surface of the titanium oxide, and a second conductive layer comprising tin oxide and provided on the first conductive layer.

2. (original) The flake-form conductive compound as recited in claim 1, wherein the first conductive layer contains 0.1 - 50 parts by weight of an antimony component in terms of antimony oxide (Sb_2O_3), based on 100 parts by weight of a tin component in terms of tin oxide (SnO_2).

3. (currently amended) The flake-form conductive compound as recited in ~~claim 1 or 2~~ claim 1, characterized as being obtainable by allowing a basic compound having an interlayer swelling effect to act on layered titanic acid to thereby delaminate the layered titanic acid into titanic acid flakes, applying a stannic compound to form said first conductive layer on the flake-form titanic acid,

applying a stannous compound to form said second conductive layer on the first conductive layer and subjecting the combination to a heat treatment.

4. (currently amended) A conductive ~~compound~~ composition comprising a binder and the flake-form conductive compound as recited in ~~any one of claims 1 - 3~~ claim 1.

5. (currently amended) The conductive composition as recited in claim 4, characterized as containing 100 parts by weight of the binder and 5 - 50 parts by weight of the flake-form conductive compound ~~as recited in any one of claims 1 - 3~~.

6. (currently amended) The conductive composition as recited in ~~claim 4 or 5~~ claim 4, wherein said binder ~~may be of~~ is at least one ~~or more types~~ selected from the group consisting of thermoplastic resins, thermosetting resins, inorganic aggregates and metal-containing organic compounds.

7. (new) The conductive composition as recited in claim 5, wherein said binder is at least one selected from the group consisting of thermoplastic resins, thermosetting resins, inorganic

aggregates and metal-containing organic compounds.

8. (new) The flake-form conductive compound as recited in claim 2, characterized as being obtainable by allowing a basic compound having an interlayer swelling effect to act on layered titanic acid to thereby delaminate the layered titanic acid into titanic acid flakes, applying a stannic compound to form said first conductive layer on the flake-form titanic acid, applying a stannous compound to form said second conductive layer on the first conductive layer and subjecting the combination to a heat treatment.

9. (new) A conductive composition comprising a binder and the flake-form conductive compound as recited in claim 8.

10. (new) The conductive composition as recited in claim 9, characterized as containing 100 parts by weight of the binder and 5 - 50 parts by weight of the flake-form conductive compound.

11. (new) The conductive composition as recited in claim 9, wherein said binder is at least one selected from the group consisting of thermoplastic resins, thermosetting resins, inorganic

aggregates and metal-containing organic compounds.

12. (new) The conductive composition as recited in claim 10, wherein said binder is at least one selected from the group consisting of thermoplastic resins, thermosetting resins, inorganic aggregates and metal-containing organic compounds.

13. (new) A conductive composition comprising a binder and the flake-form conductive compound as recited in claim 2.

14. (new) The conductive composition as recited in claim 13, characterized as containing 100 parts by weight of the binder and 5 - 50 parts by weight of the flake-form conductive compound.

15. (new) The conductive composition as recited in claim 13, wherein said binder is at least one selected from the group consisting of thermoplastic resins, thermosetting resins, inorganic aggregates and metal-containing organic compounds.

16. (new) The conductive composition as recited in claim 14, wherein said binder is at least one selected from the group consisting of thermoplastic resins, thermosetting resins, inorganic

aggregates and metal-containing organic compounds.

17. (new) A conductive composition comprising a binder and the flake-form conductive compound as recited in claim 3.

18. (new) The conductive composition as recited in claim 17, characterized as containing 100 parts by weight of the binder and 5 - 50 parts by weight of the flake-form conductive compound.

19. (new) The conductive composition as recited in claim 17, wherein said binder is at least one selected from the group consisting of thermoplastic resins, thermosetting resins, inorganic aggregates and metal-containing organic compounds.

20. (new) The conductive composition as recited in claim 18, wherein said binder is at least one selected from the group consisting of thermoplastic resins, thermosetting resins, inorganic aggregates and metal-containing organic compounds.